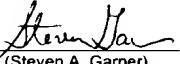




I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as First Class Mail, in an envelope addressed to: Commissioner for Patents, P. O. Box 1450, Alexandria VA 22313-1450, on the date shown below.

Dated: May 5, 2003

Signature: 
(Steven A. Garner)

7823
#9
5/14/03
Mallish

Docket No.: TESSERA 3.0-255
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of: :
Warner et al :
Application No.: 09/811,803 ✓ : Group Art Unit: 2823
Filed: March 19, 2001 ✓ : Examiner: F. Toledo
For: METHODS OF MAKING :
MICROELECTRONIC ASSEMBLIES :
USING COMPRESSED RESILIENT :
LAYER :
Commissioner for Patents
P. O. Box 1450
Alexandria, VA 22313-1450

RESPONSE

Dear Sir:

Applicant submits the within communication in response to the Official Action mailed February 5, 2003.

Applicant respectfully requests reconsideration and allowance of claims 1-38 that are pending in the instant application.

Claims 1-6, 17-20 and 23-38 were rejected under 35 U.S.C. § 102(b) as being anticipated by DiStefano et al., U.S. Patent 5,518,964. The Examiner has stated that DiStefano discloses a first resilient element disposed between the first side assembly and the second side assembly, applying a compressive force to the juxtaposed assemblies so as to compress the first resilient element, and at least partially releasing the compressive force, so as to allow the first resilient element to expand, thereby moving one or both of the first side assembly and the second side assembly to deform the leads. (Official Action at 2.) However, the teachings in DiStefano relied upon by the Examiner do not describe any resilient

element which is present between the first side assembly and the second side assembly and which is compressed and then released so as to move the first side or second side assembly and thereby deform the leads, all as recited in claim 1. One example of these features is shown in Figs. 7 and 8 of the present drawings. A resilient element 25 is compressed between a first side assembly 1 and a second side assembly 8. Leads 18 extend between the first side and second side assemblies. When the compression is released, the resilient element 25 expands (Fig. 8) and moves the assemblies 1 and 8 away from one another, thereby deforming the leads 18.

The embodiment of *DiStefano* relied upon by the Examiner discloses no such operation of a resilient element. This embodiment uses a dielectric sheet 34 and a wafer 86 held firmly against platens 105 and 94 through the application of vacuum. The platens are then moved relative to one another by moving one or both of the platens so that platen 94 and, hence, the chip or second element 86 moves vertically away from platen 105 and away from the dielectric sheet or first element 34, in the direction indicated by the arrow V1. (Fig. 15; col. 13, lns. 7-17.) At the same time, platen 94 and the wafer or second element 86 are moved horizontally relative to platen 105 and the sheet or first element 34 in a horizontal direction D2 to the left, thereby forming each lead into a vertically extensive, generally S-shaped and curved structure. During or after the lead-forming step, while the dielectric sheet 34 and wafer 86 are still in their moved positions and still engaged with the platens 105 and 94, a flowable, curable dielectric material 108 is injected into the space between the dielectric sheet 34 and the wafer 86. (Col. 14, lns. 17-21.) Whether or not this dielectric material forms a resilient element between the first side assembly and the second side assembly, is immaterial, because there is no suggestion that any element formed from

dielectric material 108 be compressed and then released so as to move the assemblies and deform the leads. Indeed, in this embodiment any contendable resilient element formed from material 108 is not formed until after the elements have already been moved away from one another and the leads have already been deformed. Therefore, the rejection should be withdrawn as to claim 1.

The rejection should also be withdrawn as to claims 2-6, 17-20 and 23-38, inasmuch as each of these claims depends, directly or indirectly, from claim 1.

Claims 7-16, 21 and 22 were not rejected but instead were objected to as depending from a rejected base claim. This objection should be withdrawn inasmuch as claim 1 is believed allowable.

As it is believed that all of the rejections and objections set forth in the Official Action have been fully met, favorable reconsideration and allowance are earnestly solicited.

If, however, for any reason the Examiner does not believe that such action can be taken at this time, it is respectfully requested that he telephone applicant's attorney at (908) 654-5000 in order to overcome any additional objections which he might have.

If there are any additional charges in connection with this requested amendment, the Examiner is authorized to charge Deposit Account No. 12-1095 therefor.

Dated: May 5, 2003

Respectfully submitted,

By Steven A. Garner
Steven A. Garner
Registration No.: 52,475
LERNER, DAVID, LITTENBERG,
KRUMHOLZ & MENTLIK, LLP
600 South Avenue West
Westfield, New Jersey 07090
(908) 654-5000
Attorneys for Applicant